

FIG. 1

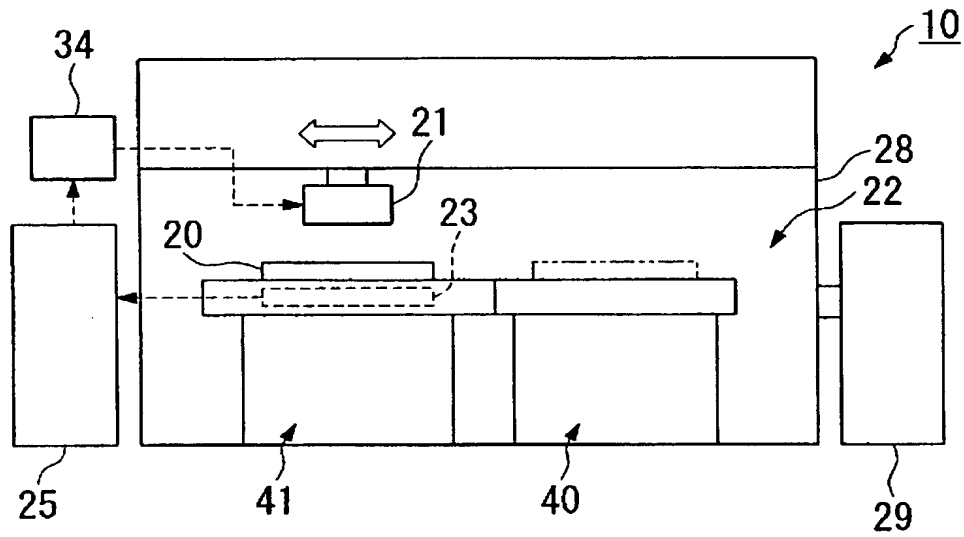


FIG. 2

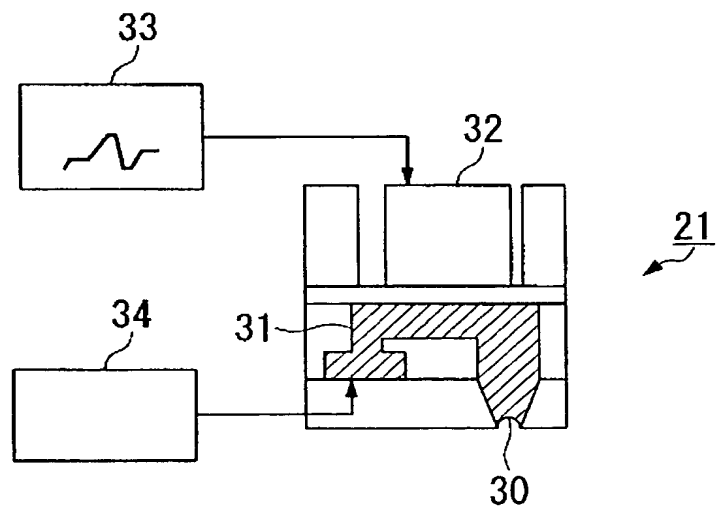


FIG. 3A

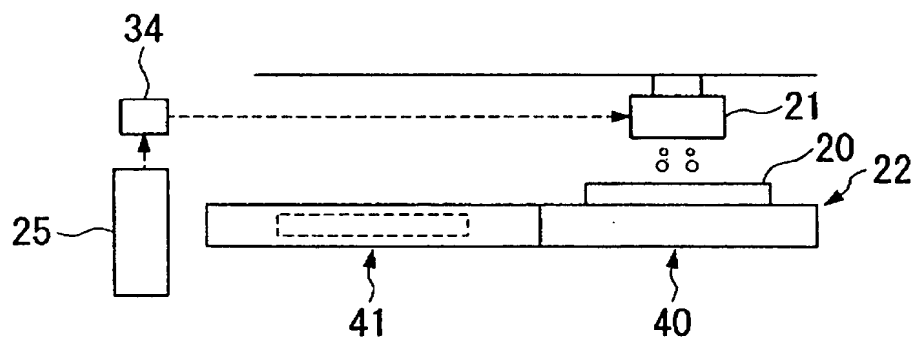


FIG. 3B

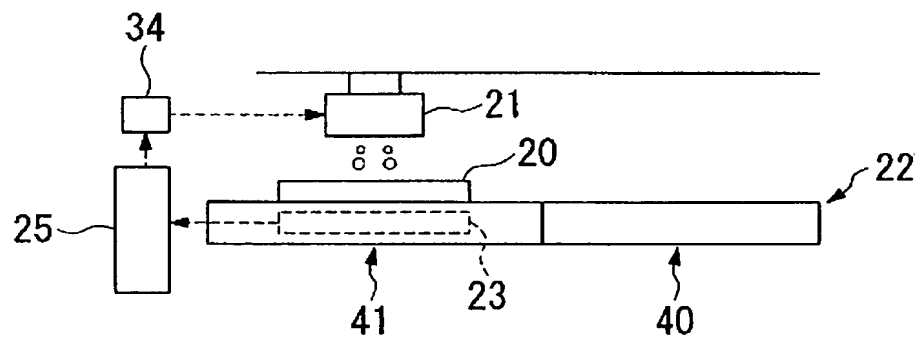


FIG. 4

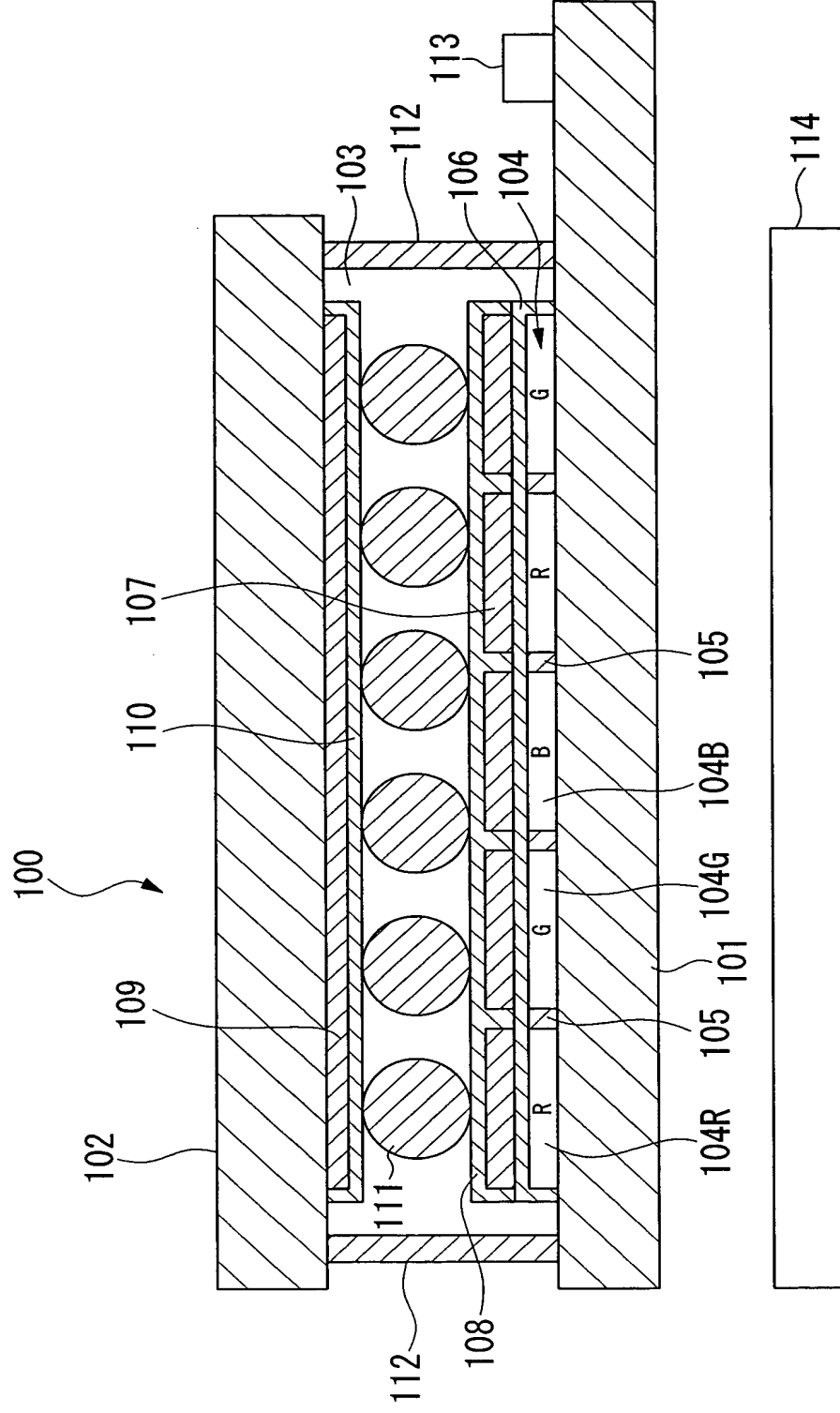


FIG. 5A

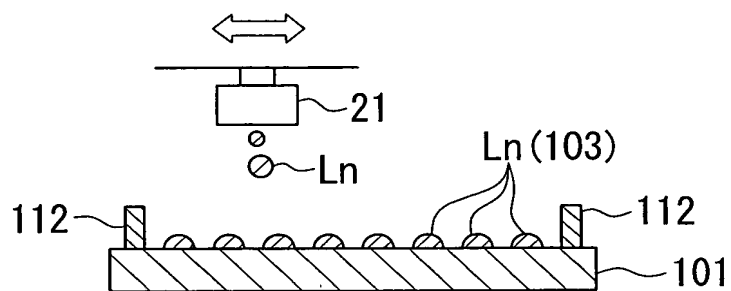


FIG. 5B

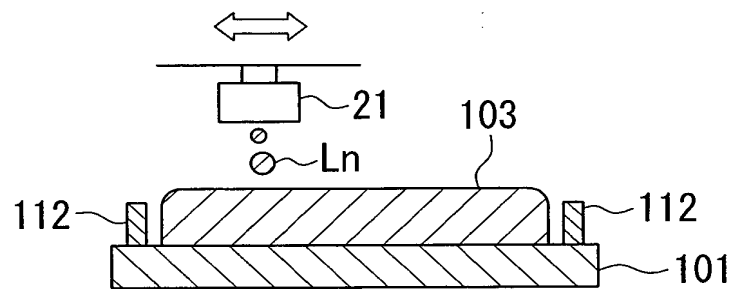


FIG. 5C

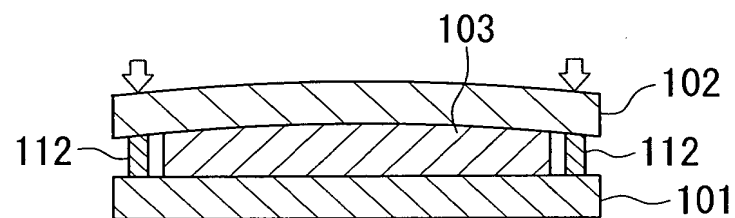


FIG. 5D

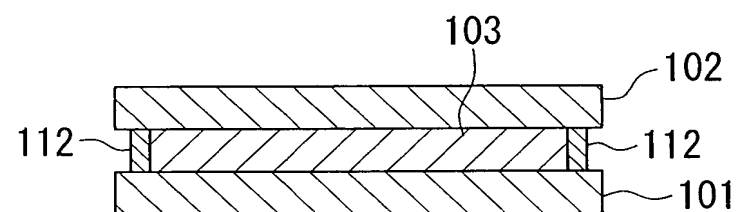


FIG. 6

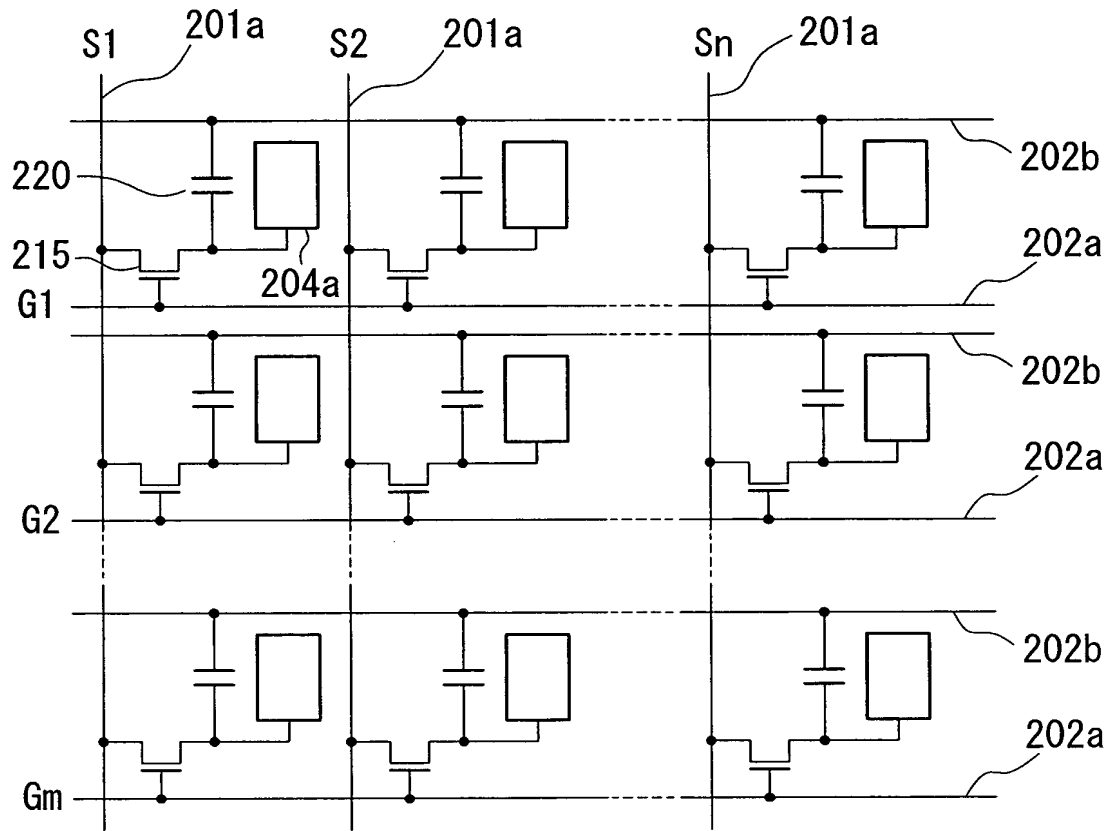
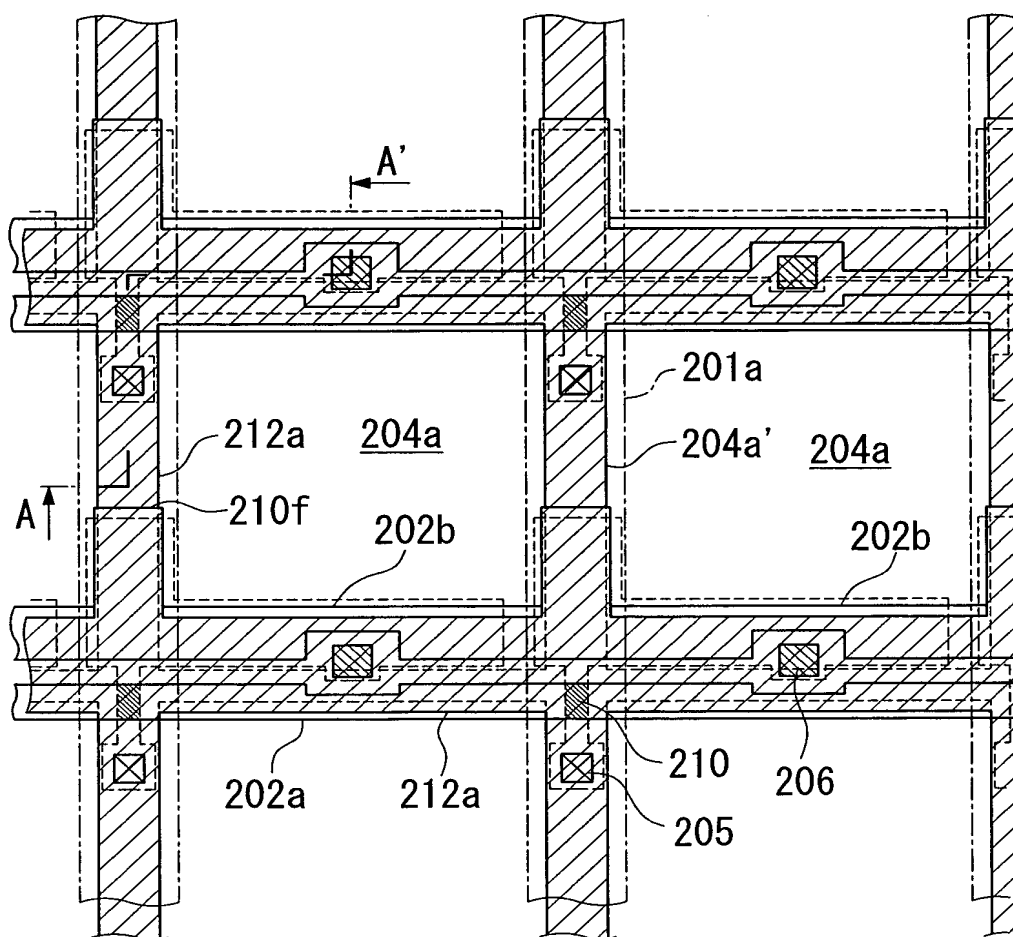


FIG. 7



230

FIG. 8

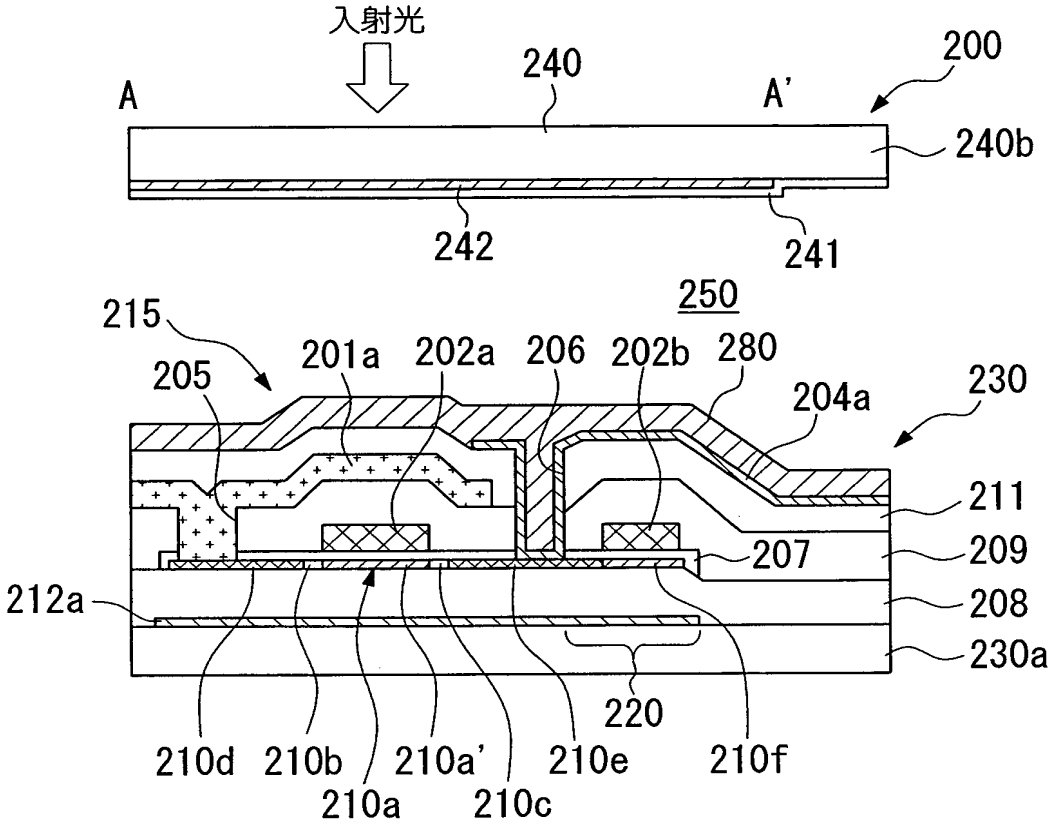


FIG. 9

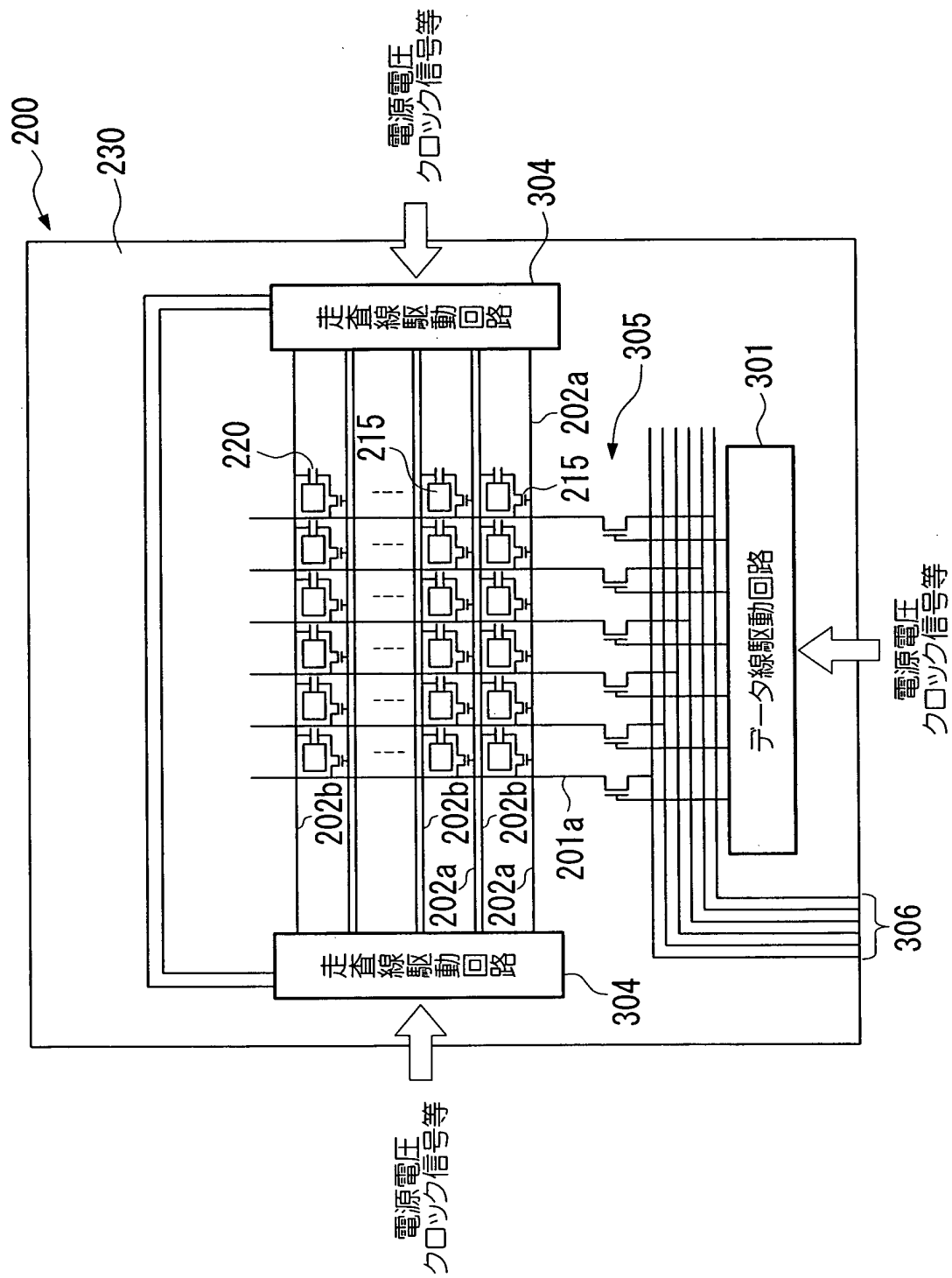




FIG. 10A

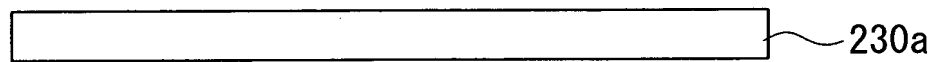


FIG. 10B

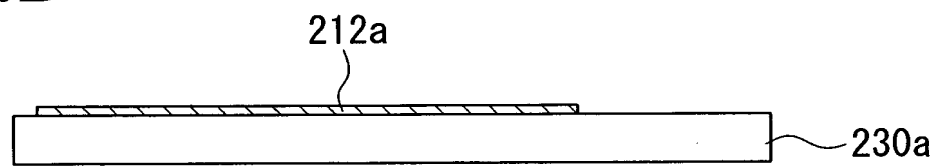


FIG. 10C

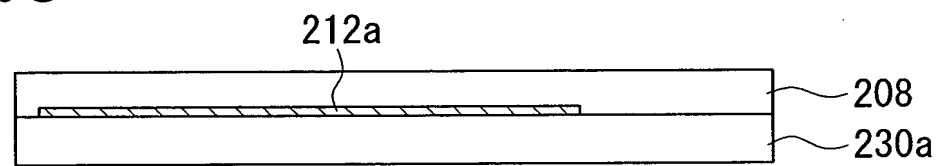


FIG. 11A

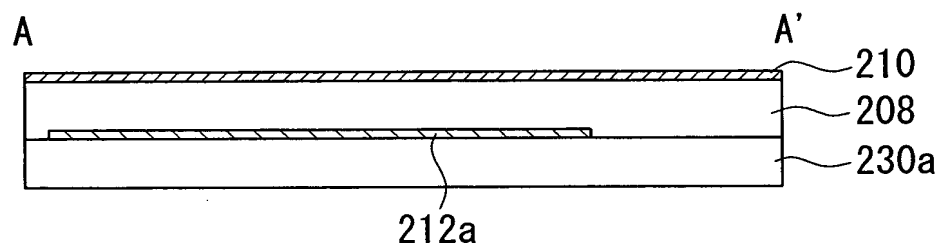


FIG. 11B

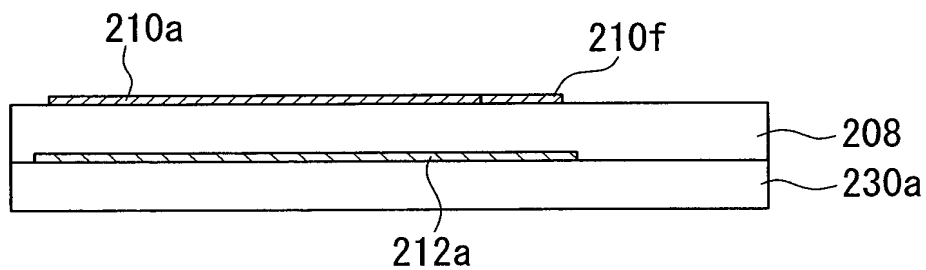


FIG. 11C

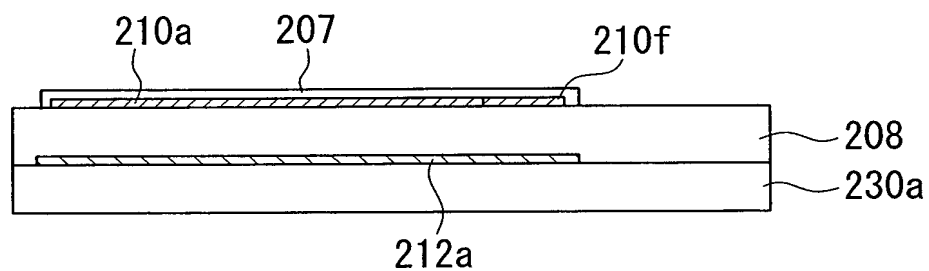


FIG. 11D

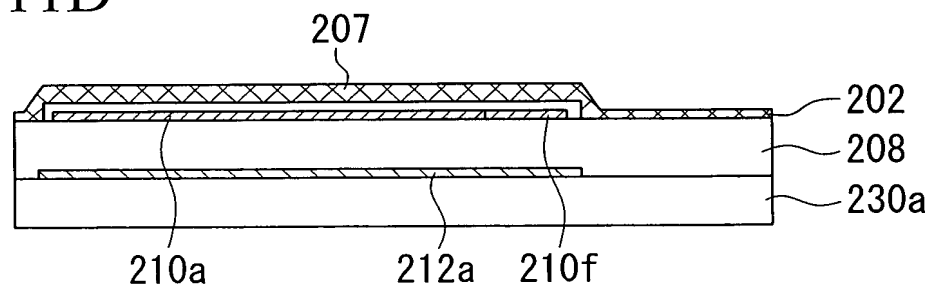


Figure 12B is a cross-sectional view of a semiconductor device 12B. The device includes a substrate 230a, a first layer 210a, a second layer 210b, and a third layer 210c. A fourth layer 212a is formed on the second layer 210b. A fifth layer 210f is formed on the fourth layer 212a. A sixth layer 207 is formed on the fifth layer 210f. A seventh layer 202a is formed on the sixth layer 207, and an eighth layer 202b is formed on the sixth layer 207. A ninth layer 208 is formed on the seventh layer 202a and the eighth layer 202b. A bracket 260 indicates a region of the device.

Diagram D is a cross-sectional view of a semiconductor device. It shows a substrate with several layers: 210d (bottom), 210b, 210a, 210c, 210e, and 210f. A layer 212a is positioned between layers 210c and 210e. Above these layers is a layer 208, which is further covered by a layer 264. The top surface of the device is patterned, with features 202a and 202b. A central region is labeled 207. The device is also labeled with 230a on the right side.

FIG. 13A

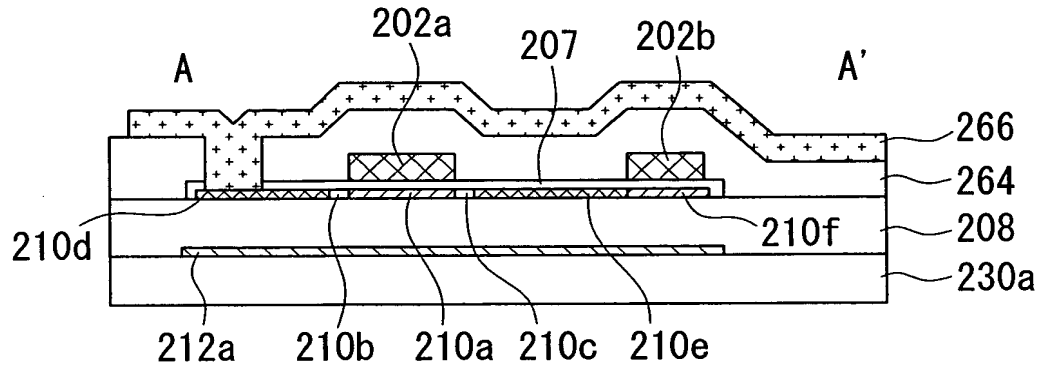


FIG. 13B

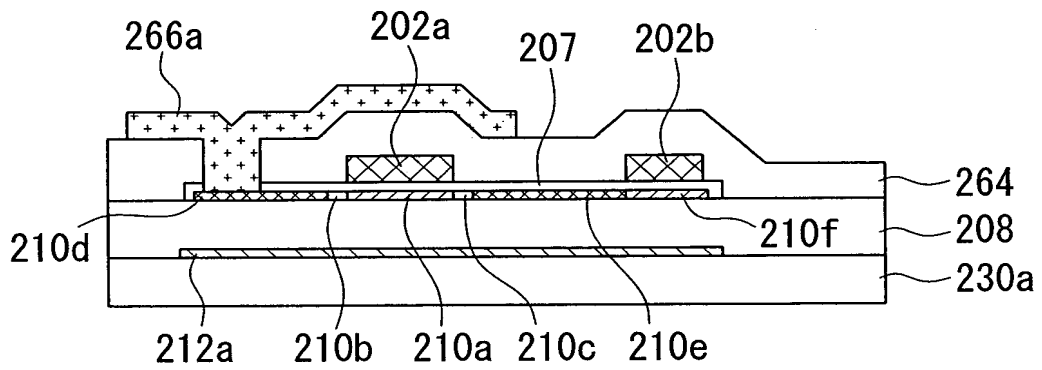


FIG. 13C

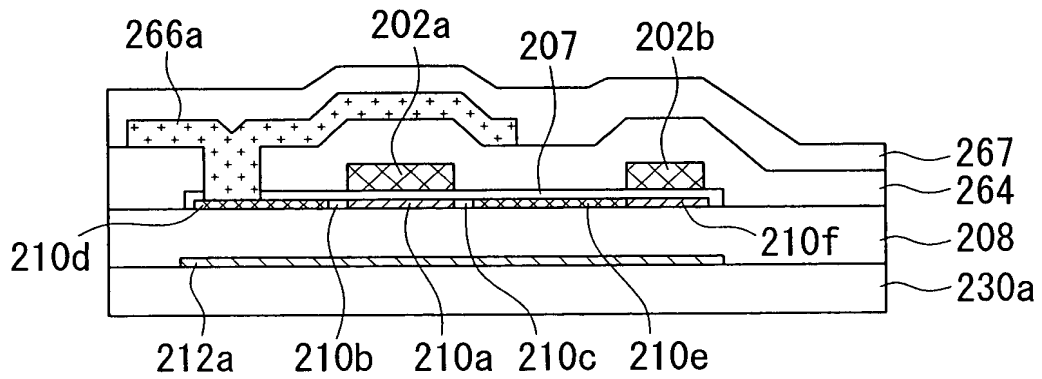


FIG. 14A

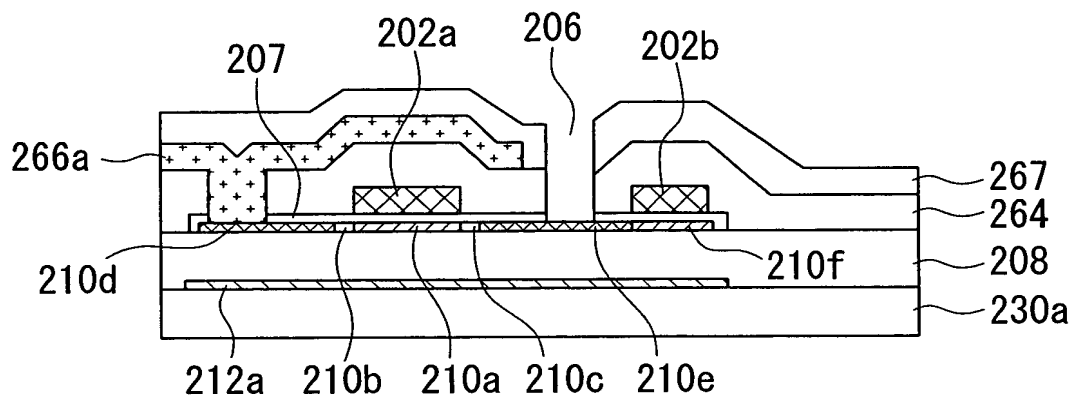


FIG. 14B

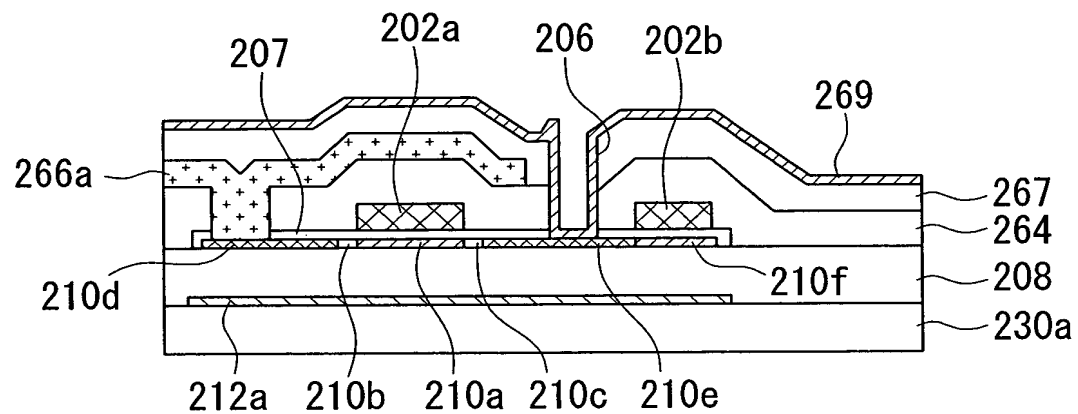


FIG. 14C

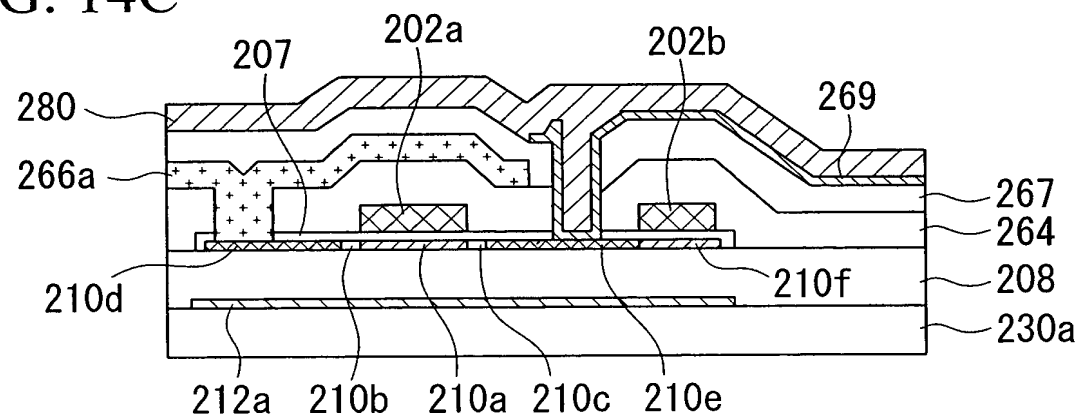


FIG. 15

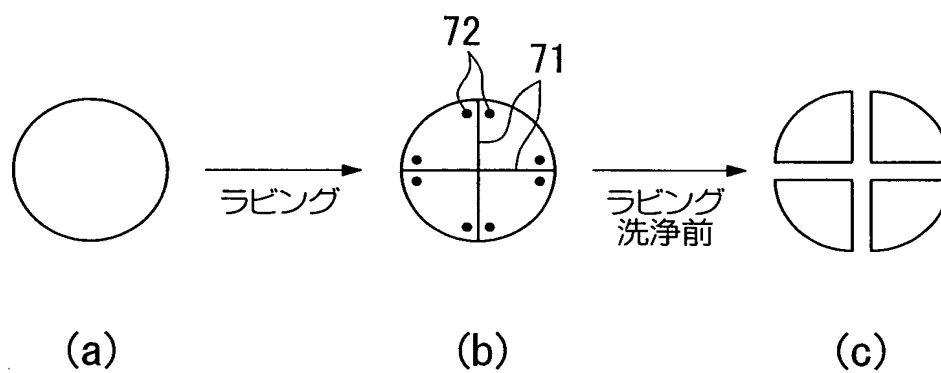


FIG. 16

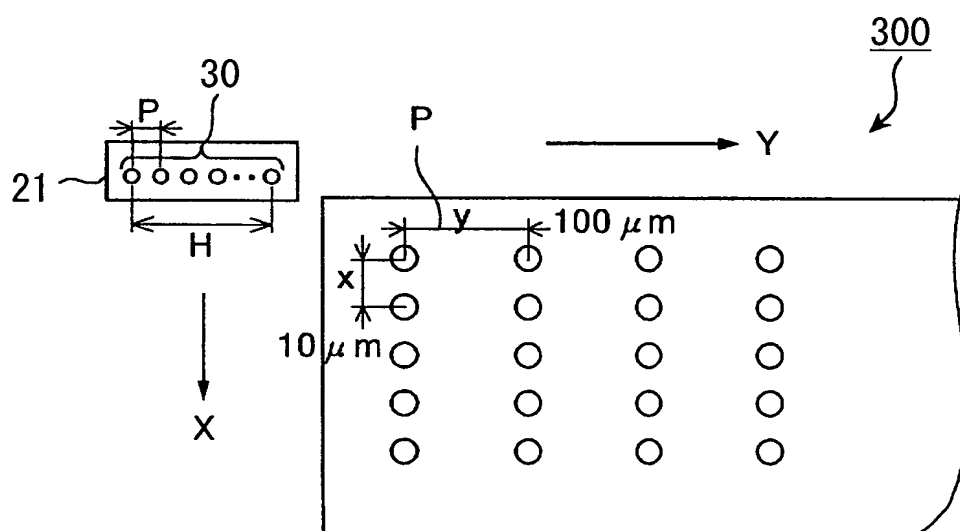


FIG. 17

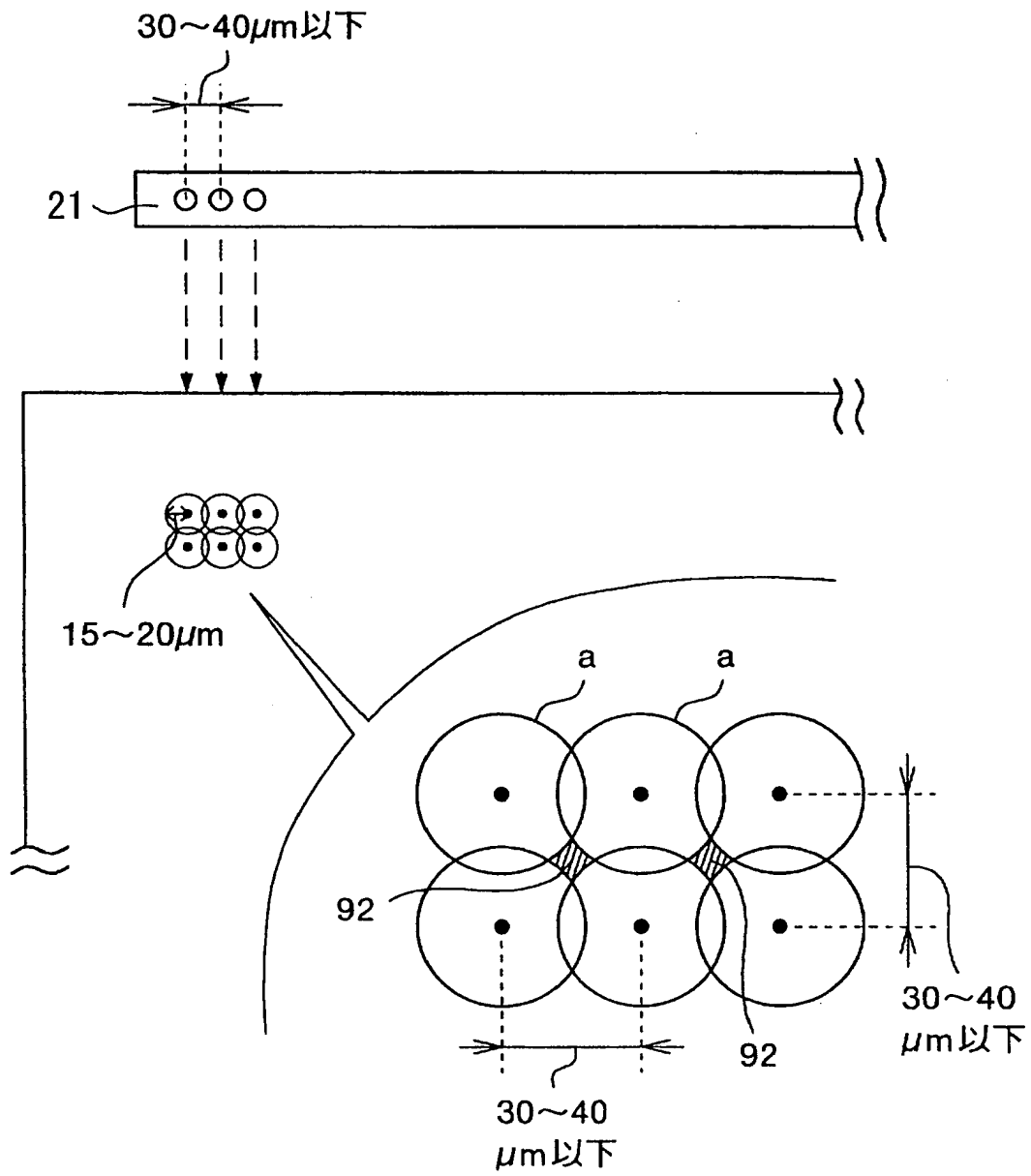


FIG. 18

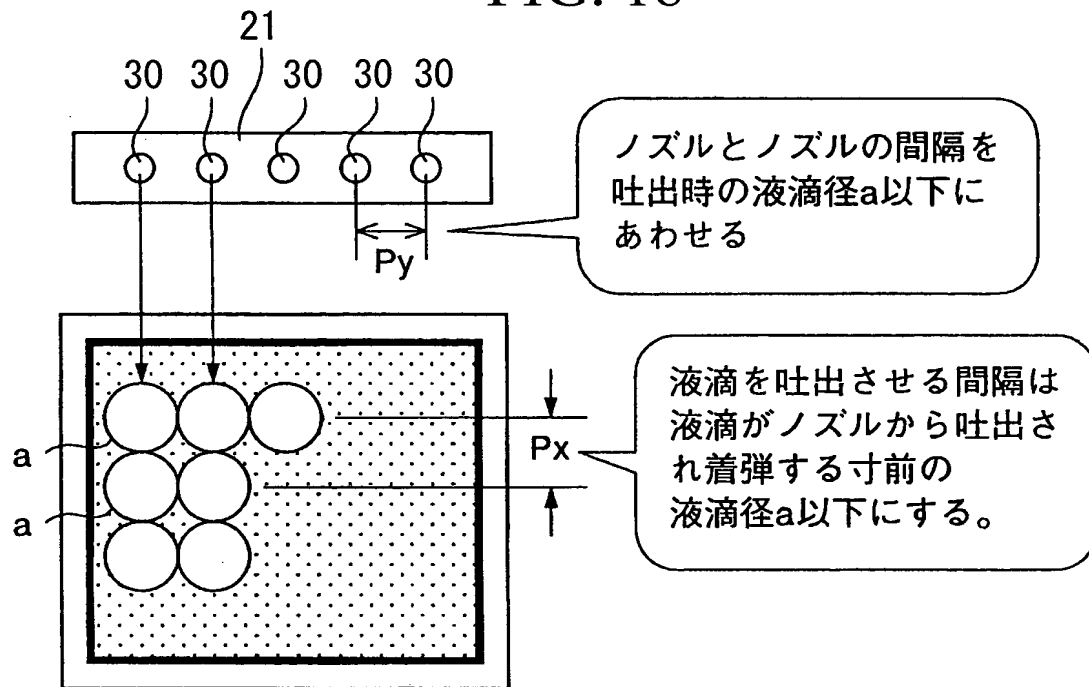


FIG. 19

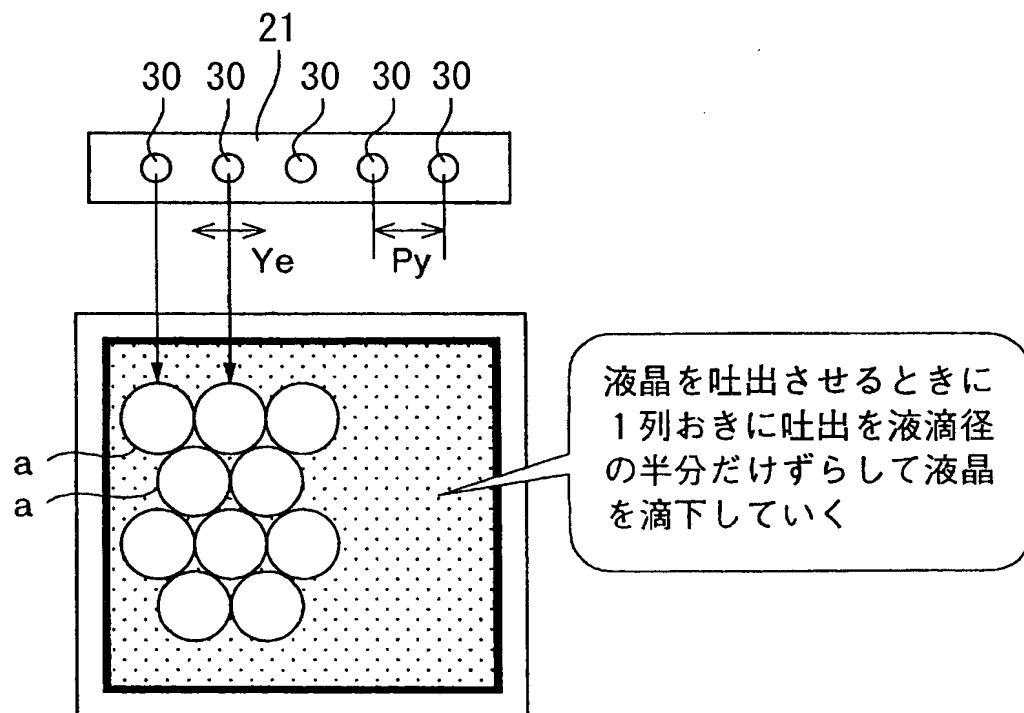




FIG. 20

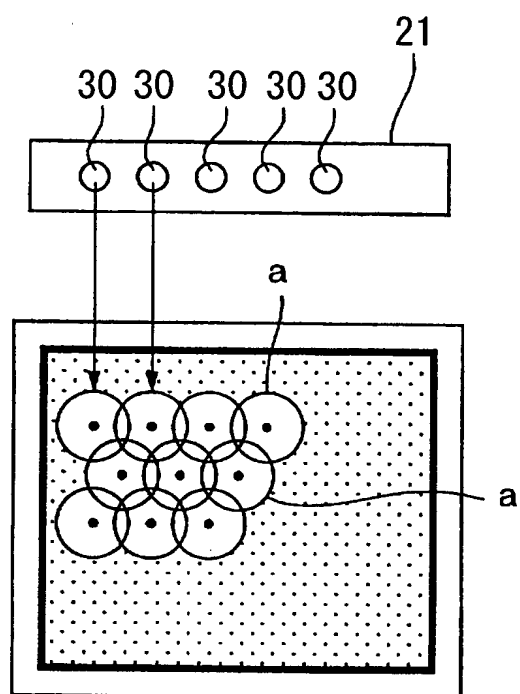


FIG. 21

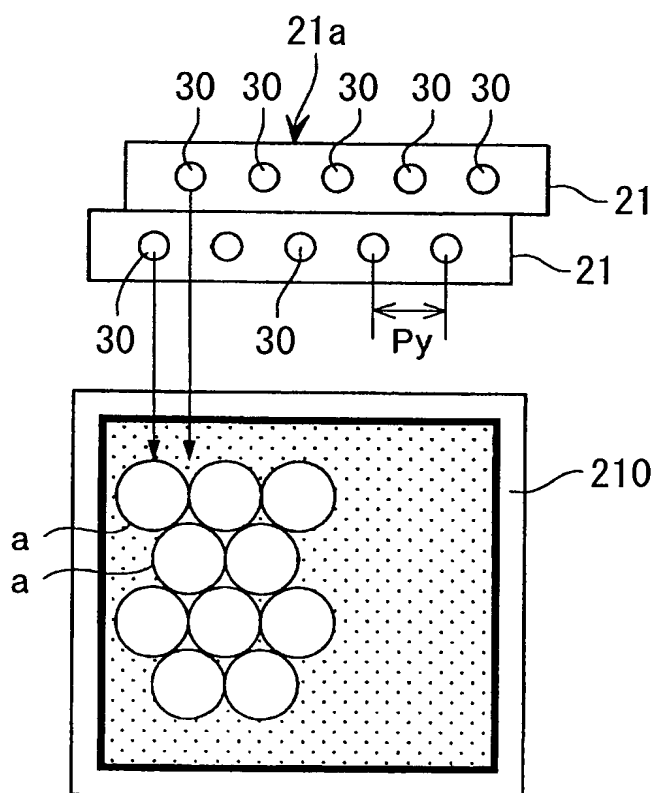


FIG. 22

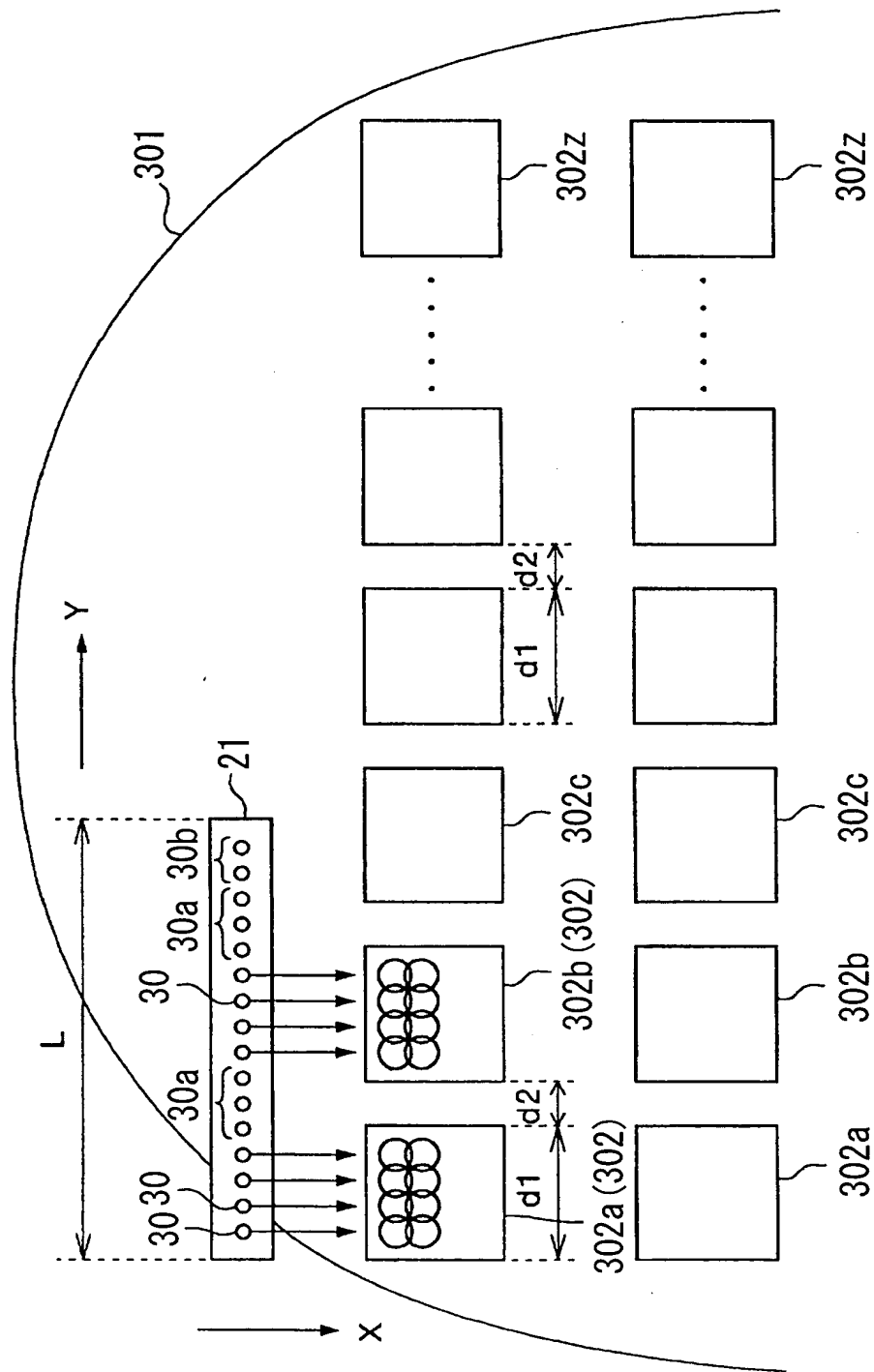


FIG. 23

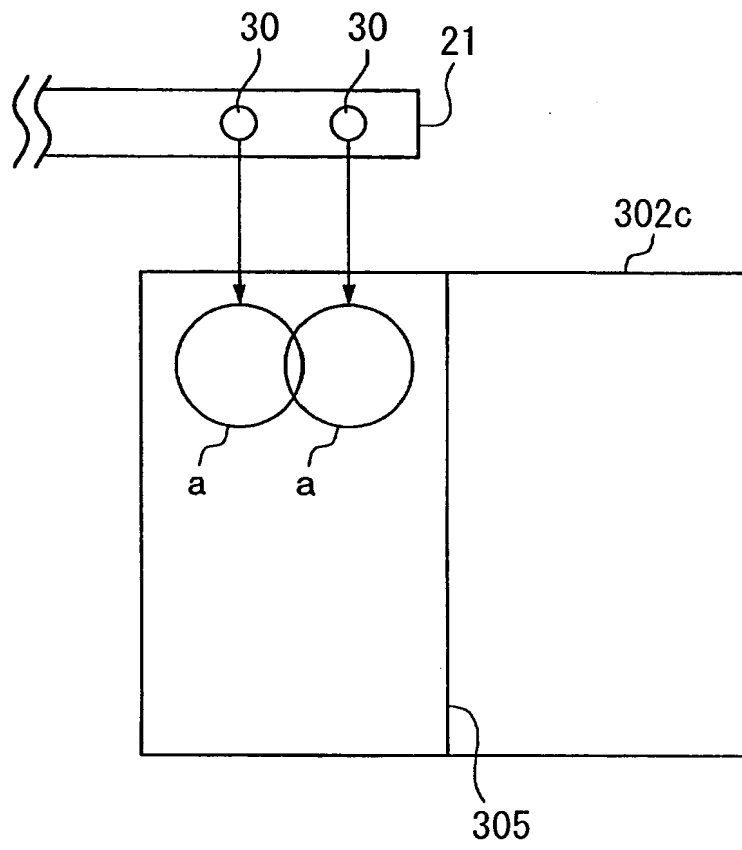


FIG. 24

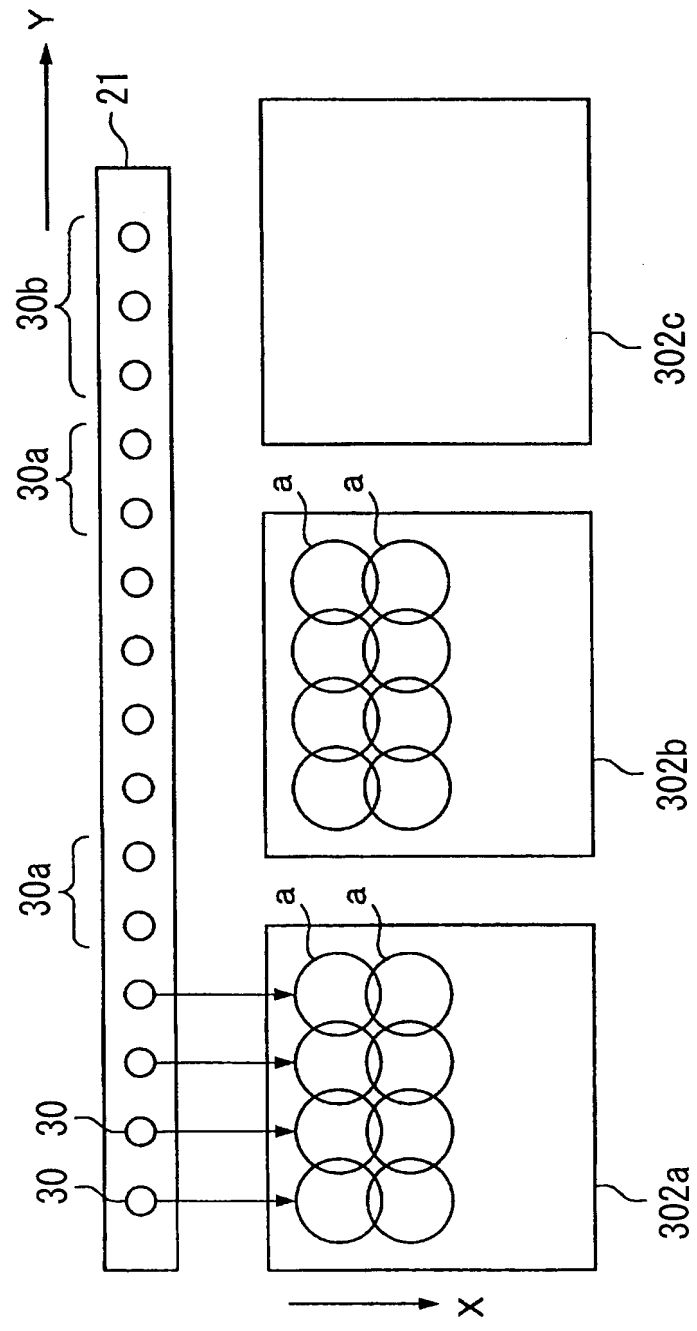


FIG. 25

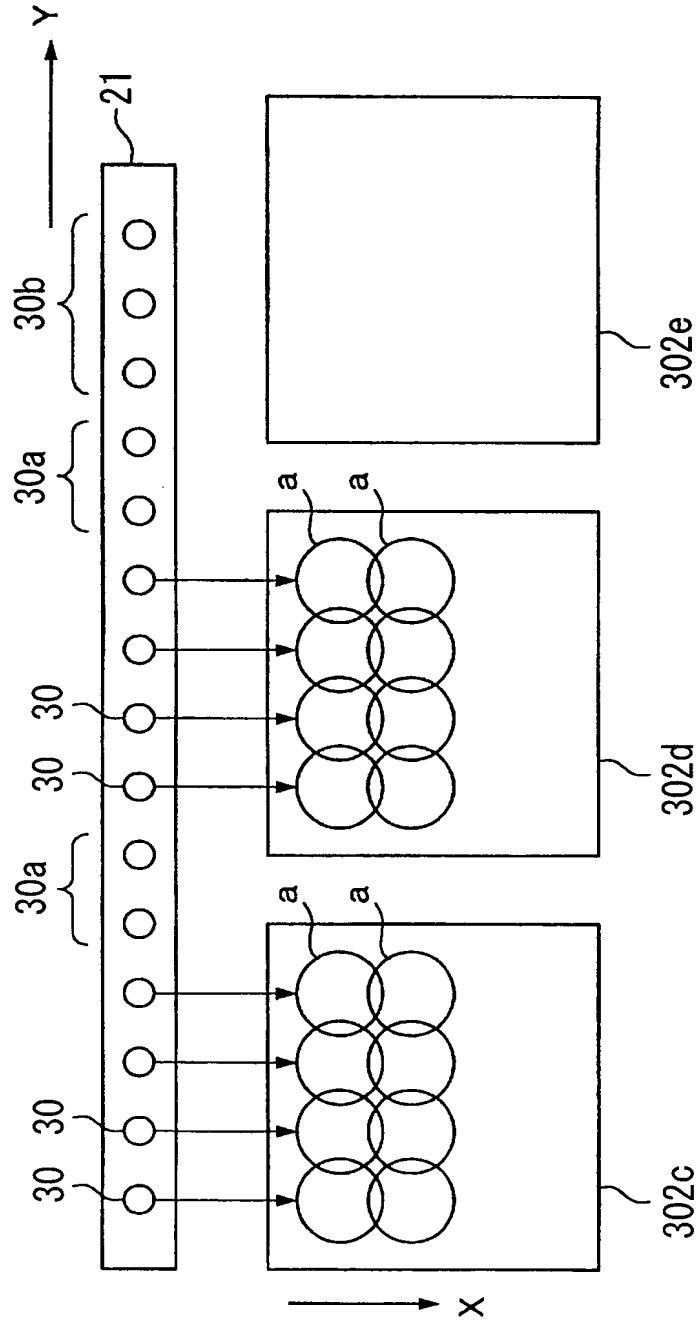


FIG. 26

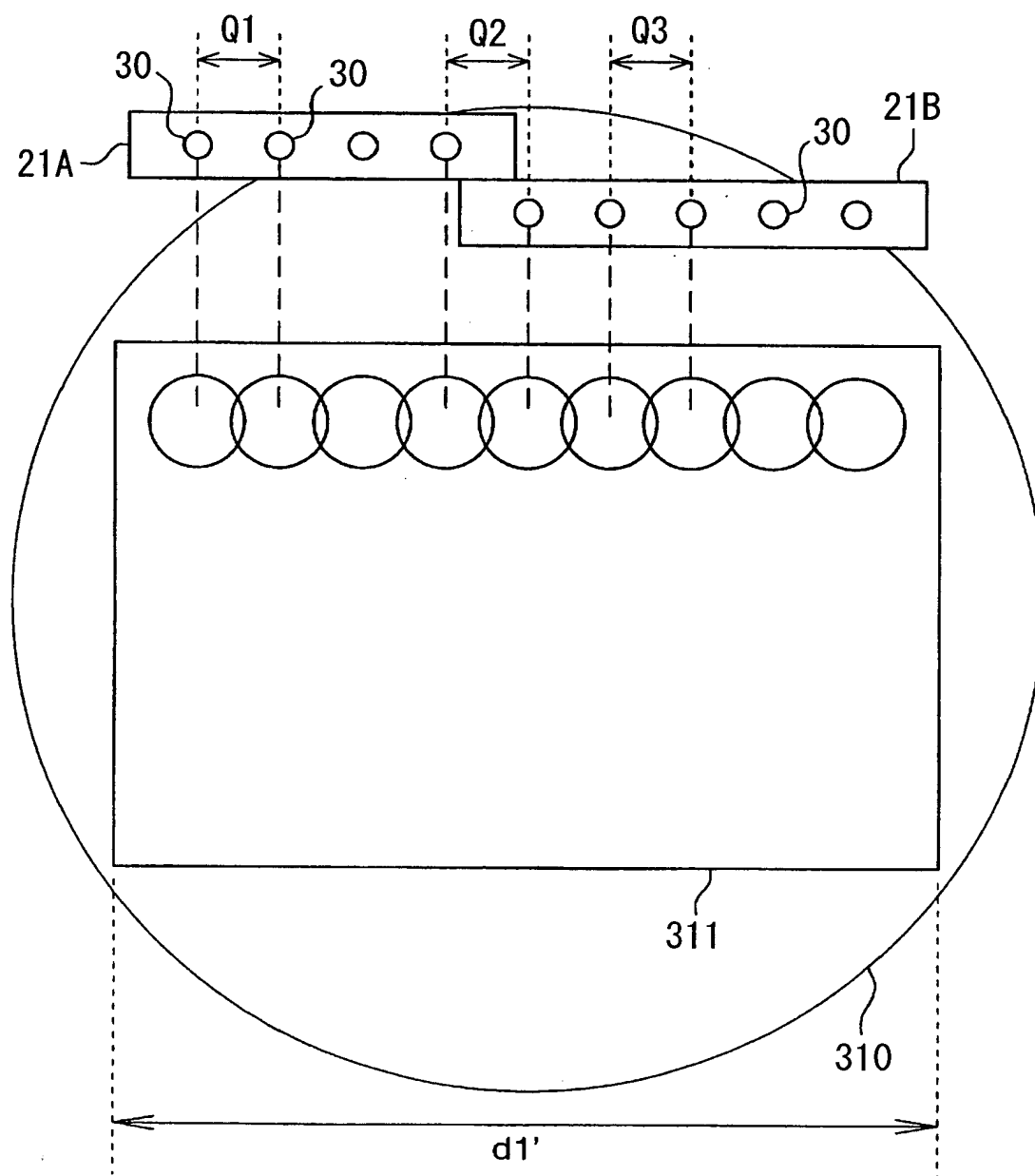


FIG. 27A

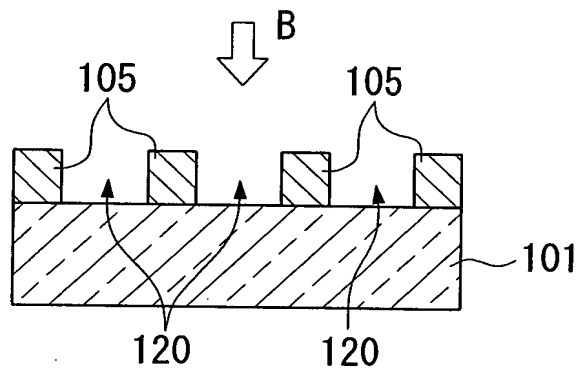


FIG. 27B

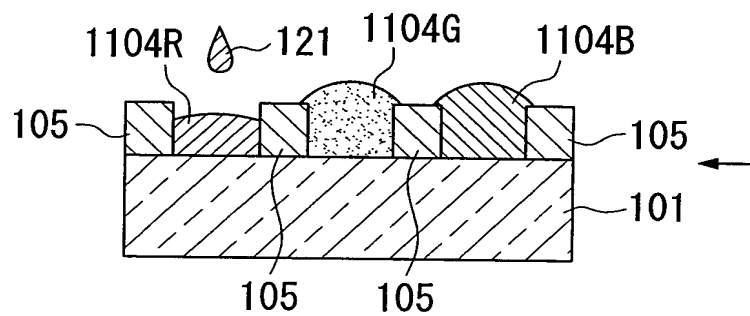


FIG. 27C

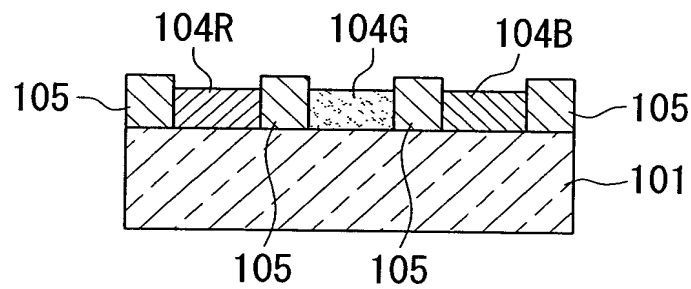


FIG. 27D

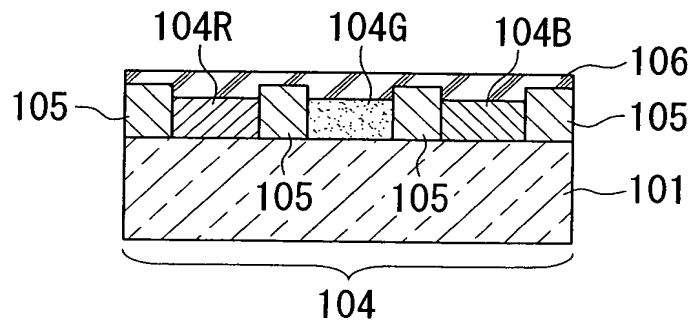


FIG. 28

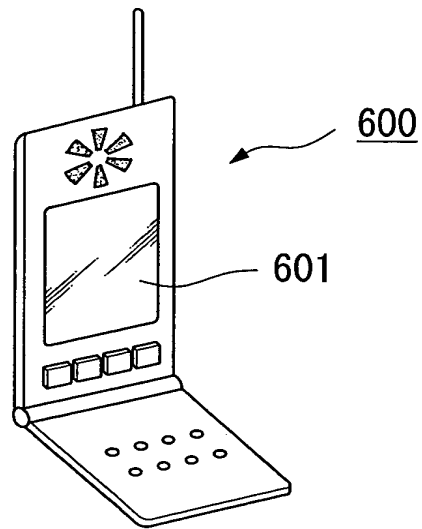


FIG. 29

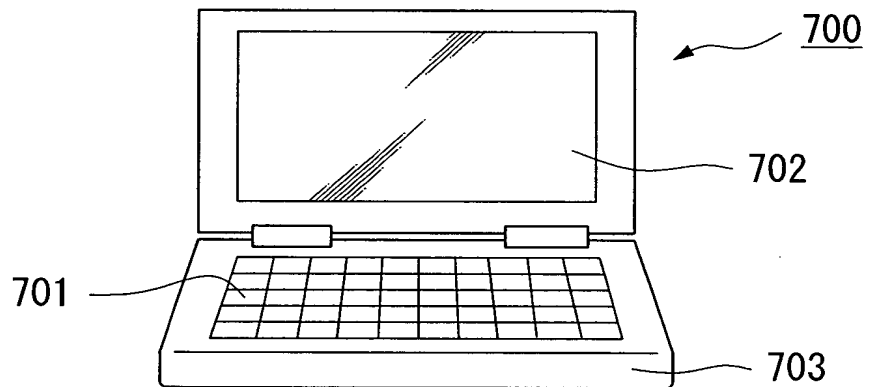


FIG. 30

